

# SOT728-2

plastic, low profile ball grid array package; 324 balls; 1 mm pitch; 19 mm x 19 mm x 1 mm body

11 October 2018

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LPGA324
<b>Package type industry code</b>	LPGA324
<b>Package style descriptive code</b>	LBGA (low profile ball grid array)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-192
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	25-05-2005
<b>Manufacturer package code</b>	SOT728

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	18.8	19	19.2	mm
package width	18.8	19	19.2	mm
seated height	-	1.55	1.55	mm
package height	0.9	1	1.1	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	324	-	



## 2 Package outline

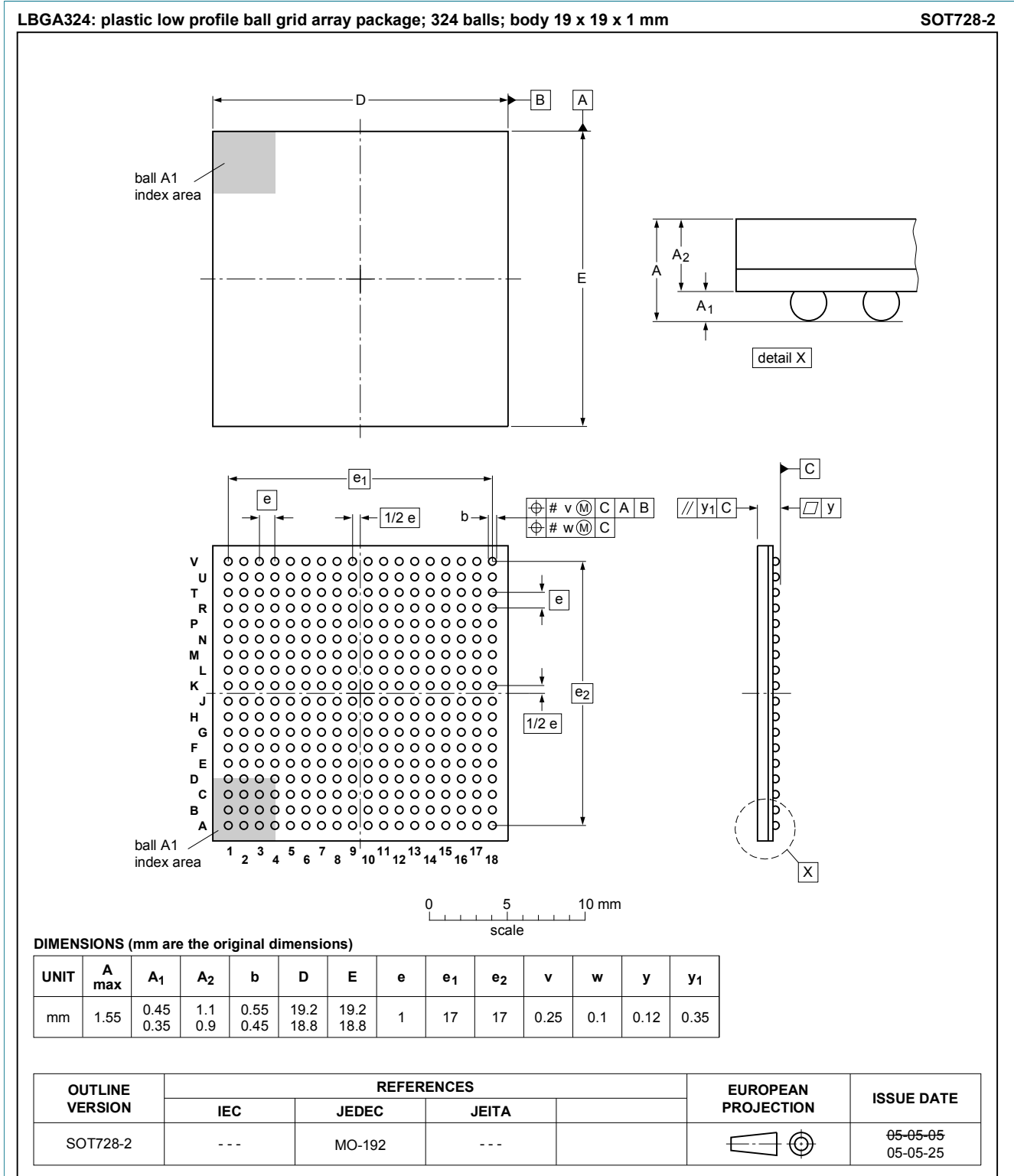


Figure 1. Package outline LPGA324 (SOT728-2)

### 3 Soldering

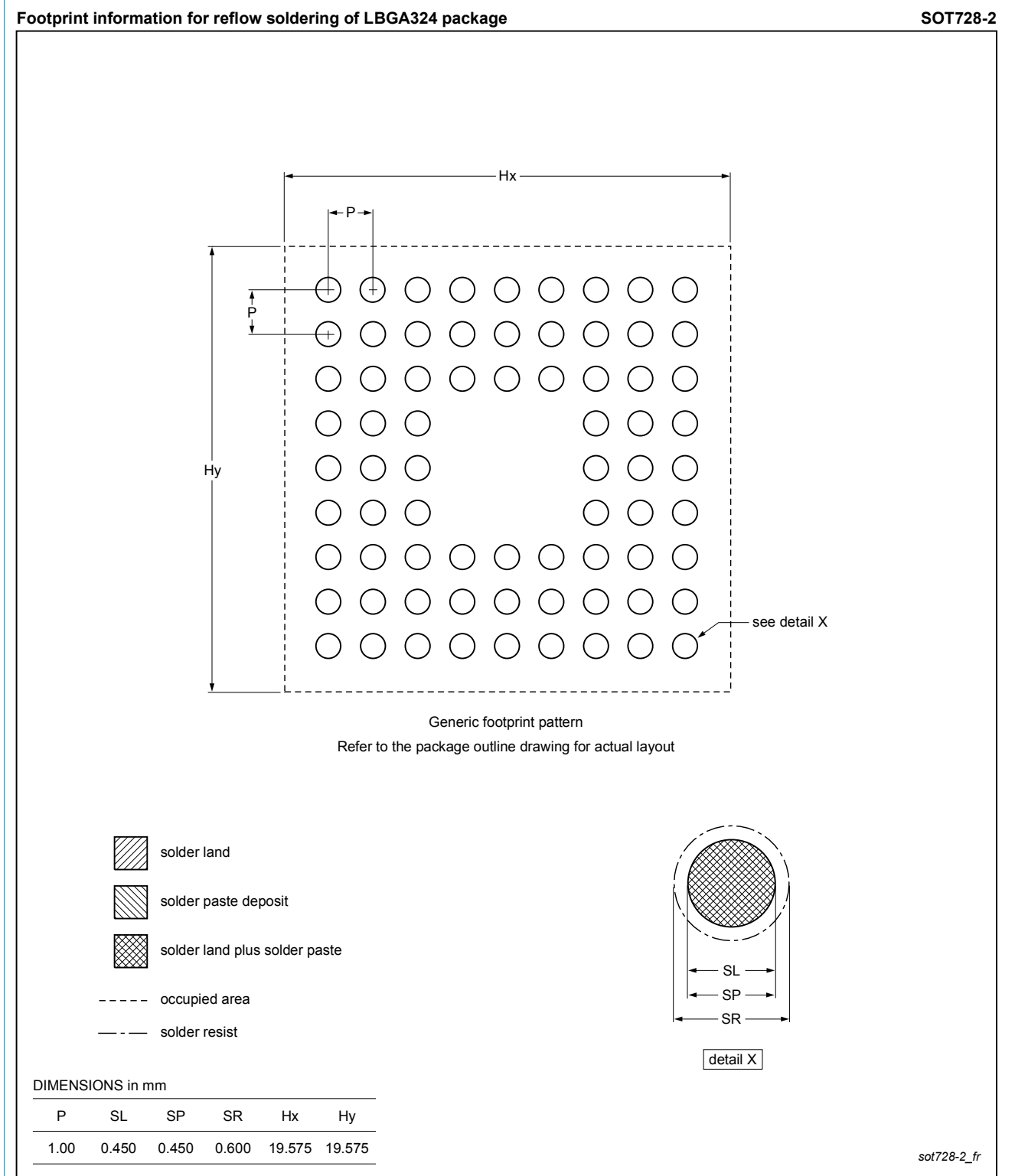


Figure 2. Reflow soldering footprint for LBG324 (SOT728-2)

## 4 Legal information

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Contents

1 Package summary .....1  
2 Package outline .....2  
3 Soldering .....3  
4 Legal information .....4